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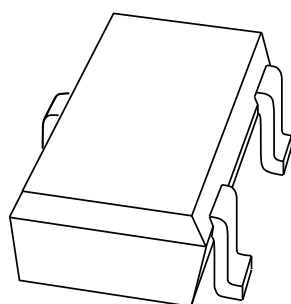
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DATA SHEET



BAP63-05W Silicon PIN diode

Product specification
Supersedes data of 2001 Apr 04

2001 May 18



Silicon PIN diode

BAP63-05W

FEATURES

- High speed switching for RF signals
- Low diode capacitance
- Low diode forward resistance
- Low series inductance
- For applications up to 3 GHz.

APPLICATIONS

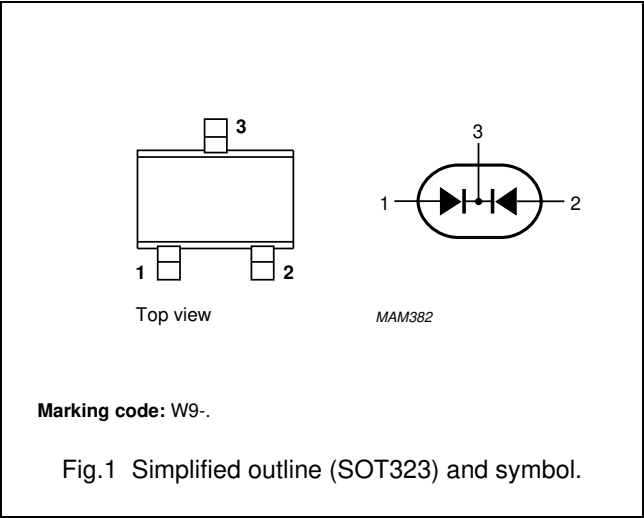
- RF attenuators and switches.

DESCRIPTION

Two planar PIN diodes in common cathode configuration in a SOT323 small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	anode (a1)
2	anode (a2)
3	common cathode



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V _R	continuous reverse voltage		–	50	V
I _F	continuous forward current		–	100	mA
P _{tot}	total power dissipation	T _s ≤ 90 °C	–	240	mW
T _{stg}	storage temperature		–65	+150	°C
T _j	junction temperature		–65	+150	°C

Silicon PIN diode

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ELECTRICAL CHARACTERISTICST_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
Per diode					
V _F	forward voltage	I _F = 50 mA	0.95	1.1	V
I _R	reverse current	V _R = 35 V	–	10	nA
C _d	diode capacitance	V _R = 0; f = 1 MHz	0.4	–	pF
		V _R = 1 V; f = 1 MHz	0.35	–	pF
		V _R = 20 V; f = 1 MHz	0.3	0.35	pF
r _D	diode forward resistance	I _F = 0.5 mA; f = 100 MHz; note 1	2.5	3.5	Ω
		I _F = 1 mA; f = 100 MHz; note 1	1.95	3	Ω
		I _F = 10 mA; f = 100 MHz; note 1	1.17	1.8	Ω
		I _F = 100 mA; f = 100 MHz; note 1	0.9	1.5	Ω
s ₂₁ ²	isolation	V _R = 0; f = 900 MHz	14.5	–	dB
		V _R = 0; f = 1800 MHz	9.5	–	dB
		V _R = 0; f = 2450 MHz	7.0	–	dB
s ₂₁ ²	insertion loss	I _F = 0.5 mA; f = 900 MHz	0.23	–	dB
		I _F = 0.5 mA; f = 1800 MHz	0.27	–	dB
		I _F = 0.5 mA; f = 2450 MHz	0.33	–	dB
s ₂₁ ²	insertion loss	I _F = 1 mA; f = 900 MHz	0.19	–	dB
		I _F = 1 mA; f = 1800 MHz	0.24	–	dB
		I _F = 1 mA; f = 2450 MHz	0.30	–	dB
s ₂₁ ²	insertion loss	I _F = 10 mA; f = 900 MHz	0.14	–	dB
		I _F = 10 mA; f = 1800 MHz	0.19	–	dB
		I _F = 10 mA; f = 2450 MHz	0.25	–	dB
s ₂₁ ²	insertion loss	I _F = 100 mA; f = 900 MHz	0.11	–	dB
		I _F = 100 mA; f = 1800 MHz	0.17	–	dB
		I _F = 100 mA; f = 2450 MHz	0.23	–	dB
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R = 6 mA; R _L = 100 Ω; measured at I _R = 3 mA	310	–	ns
L _S	series inductance	I _F = 100 mA; f = 100 MHz	1.5	–	nH

Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

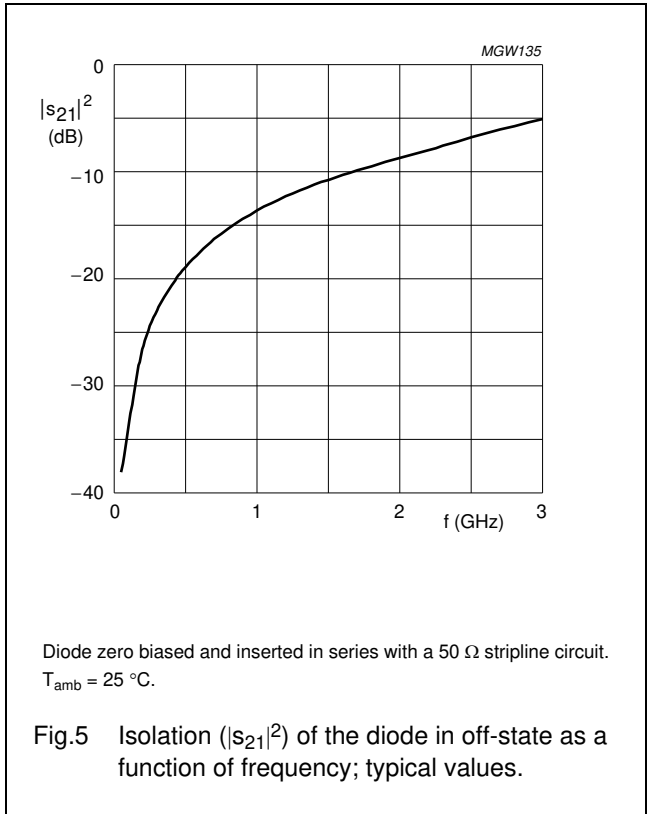
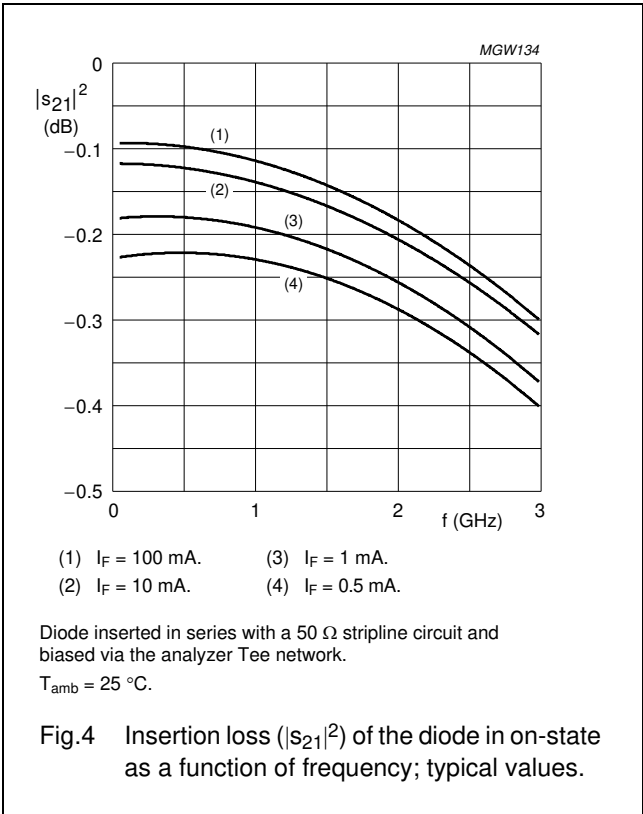
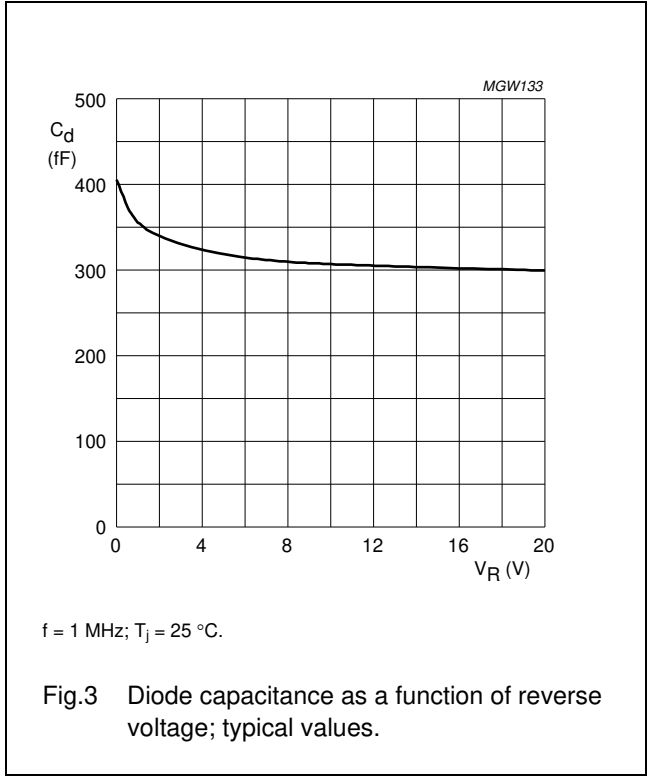
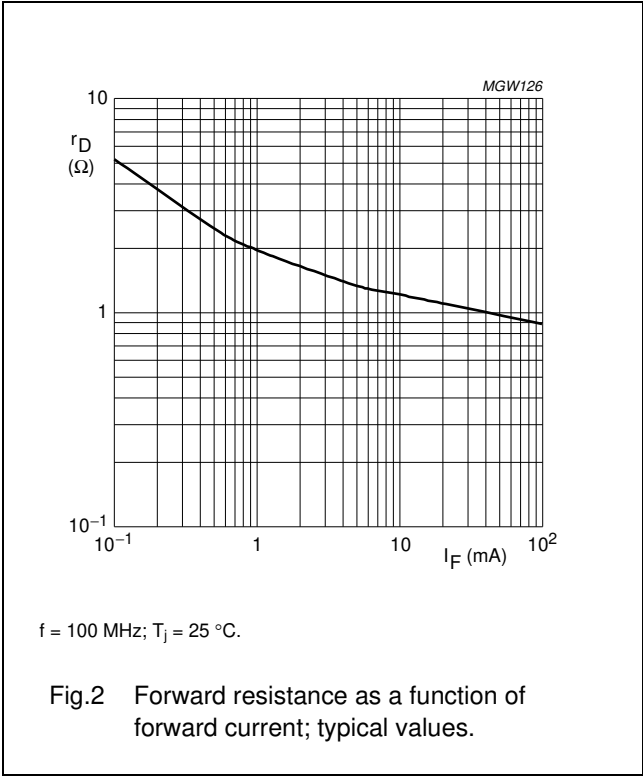
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	250	K/W

Silicon PIN diode

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GRAPHICAL DATA



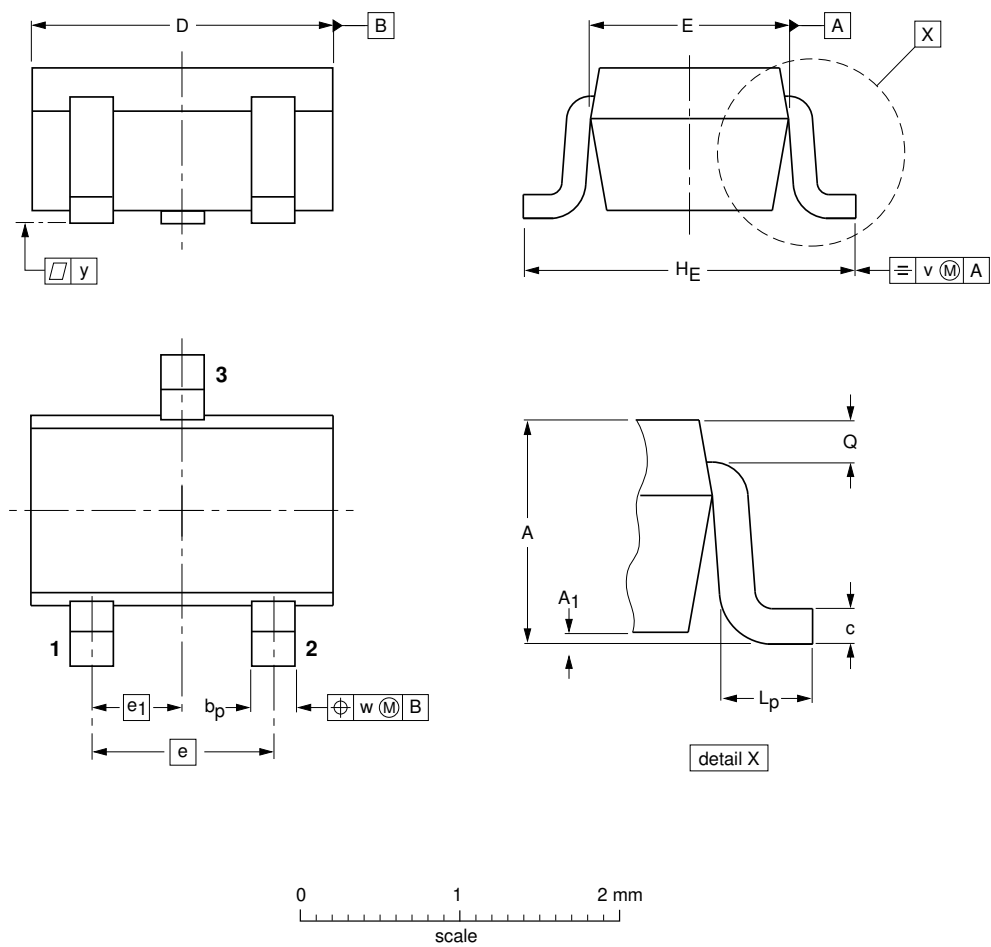
Silicon PIN diode

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PACKAGE OUTLINE

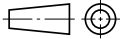
Plastic surface-mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			04-11-04 06-03-16

Silicon PIN diode

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Silicon PIN diode

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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